

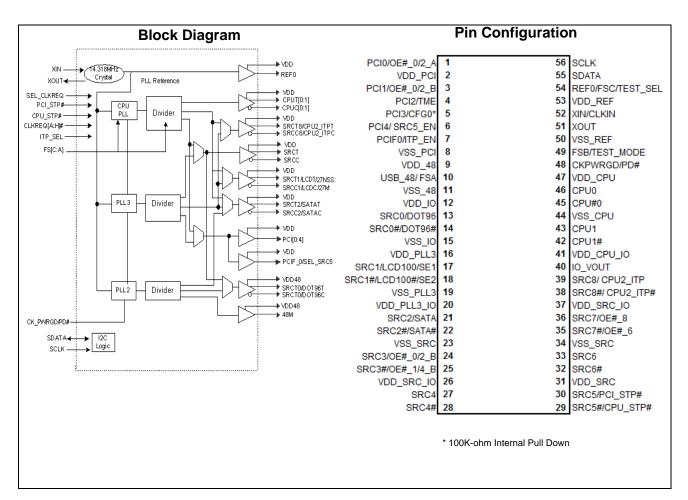
# Clock Generator for Intel® Eaglelake Chipset

#### **Features**

- Intel® CK505 Rev. 1.0 Compliant
- · Low power push-pull type differential output buffers
- PCI-Express Gen 2 Compliant SRC clocks (exclude SRC0 and SRC1)
- 8-step programmable drive strength for single-ended clocks
- Differential CPU clocks with selectable frequency
- 100 MHz Differential SRC clocks
- 100 MHz Differential LCD clock
- 96 MHz Differential DOT clock
- 48 MHz USB clock
- 33 MHz PCI clocks
- 27MHz non-spread Video clock

- 25 MHz Video clocks
- 1396 Firewire clock
- Buffered Reference Clock 14.318 MHz
- 14.318 MHz Crystal Input or Clock Input
- · Low-voltage frequency select input
- I<sup>2</sup>C support with readback capabilities
- Ideal Lexmark Spread Spectrum profile for maximum electromagnetic interference (EMI) reduction
- Industrial Temperature -40°C to 85°C
- 3.3V Power supply
- 56-pin TSSOP packages

CPU	SRC	PCI	REF	DOT96	USB_48	LCD	SE
x2/x3	x4/9	x6	x 1	x 1	x 1	x1	x2





# **56 TSSOP Pin Definition**

Pin No.	Name	Туре	Description			
1	PCI0/OE#_0/2_A	I/O, SE	3.3V, 33MHz clock/3.3V OE# Input mappable via I2C to control either SRC0 or SRC2. (Default PCI0, 33MHz clock)			
2	VDD_PCI	PWR	3.3V Power supply for PCI PLL.			
3	PCI1/OE#_1/4_B	I/O, SE	3.3V, 33MHz clock/3.3V OE# Input mappable via I2C to control either SRC1 or SRC4. (Default PCI1, 33MHz clock)			
4	PCI2/TME	I/O, SE	3.3V tolerance input for overclocking enable pin/3.3V, 33MHz clock. (Refer to DC Electrical Specifications table for Vil_FS and Vih_FS specifications,			
5	PCI3/CFG0	I/O, SE, PD	3.3V tolerant input for CPU frequency selection/3.3V 33MHz clock. (Refer to DC Electrical Specifications table for Vil_PCl3/CFG0 and Vih_PCl3/CFG0 specifications).			
			CFG PCI2/T PCI3/ PLL1 PLL2 PLL3			
			[1:0] ME CGF0 Mode Output SSC Output SSC Output SSC			
			00 x Low 0-Def CPU/SRC/PCi33 Down USB NA			
			01 x Mid 1 CPU Down USB NA SRC/PCl33 Down   10 0 High 2 CPU Center USB NA SRC/PCl33 Down			
			11 1 High 3 CPU Center USB/25M NA SRC/PCI33 Down			
0	DOLA/ODOS EN	1/0 05				
6	PCI4/SRC5_EN	1/O, SE	3.3V tolerant input to enable SRC5/3.3V, 33MHz clock. (Sampled on the CKPWRGD assertion) 1 = SRC5, 0 = CPU_STP#			
7	PCIF/ITP_EN	I/O, SE	3.3V LVTTL input to enable SRC8 or CPU2_ITP/3.3V, 33MHz clock. (Sampled on the CKPWRGD assertion) 1 = CPU2_ITP, 0 = SRC8			
8	VSS_PCI	GND	Ground for outputs.			
9	VDD_48	PWR	3.3V Power supply for outputs and PLL.			
10	USB_48/FSA	I/O	3.3V tolerant input for CPU frequency selection/fixed 3.3V, 48MHz clock output. (Refer to DC Electrical Specifications table for Vil_FS and Vih_FS specifications)			
11	VSS_48	GND	Ground for outputs.			
12	VDD_IO	PWR	0.7V Power supply for outputs.			
13	SRC0/DOT96	O, DIF	100MHz Differential serial reference clocks/Fixed 96MHz clock output. (Selected via I2C default is SRC0)			
14	SRC0#/DOT96#	O, DIF	100MHz Differential serial reference clocks/Fixed 96MHz clock output. (Selected via I2C default is SRC0)			
15	VSS_IO	GND	Ground for PLL2.			
16	VDD_PLL3	PWR	3.3V Power supply for PLL3			
17	SRC1/LCD100/SE1	O, DIF, SE	100MHz Differential serial reference clocks/100MHz LCD video clock/SE1 clocks. (Default SRC1, 100MHz clock)			
18	SRC1#/LCD100#/SE2	O, DIF, SE	100MHz Differential serial reference clocks/100MHz LCD video clock/SE2 clocks. (Default SRC1, 100MHz clock)			
19	VSS_PLL3	GND	Ground for PLL3.			
20	VDD_PLL3_IO	PWR	IO Power supply for PLL3 outputs.			
21	SRC2/SATA	O, DIF	100MHz Differential serial reference clocks.			
22	SRC2#/SATA#	O, DIF				
23	VSS_SRC	GND	Ground for outputs.			
24	SRC3/OE#_0/2_B	I/O, Dif	100MHz Differential serial reference clocks / 3.3V OE#_0/2_B, input, mappable via I2C to control either SRC0 or SRC2. (Default SRC3, 100MHz clock)			
25	SRC3#OE#_1/4_B	I/O, Dif	100MHz Differential serial reference clocks / 3.3V OE#_1/4_B input, mappable via I2C to control either SRC1 or SRC4. (Default SRC3, 100MHz clock)			



# **56 TSSOP Pin Definition** (continued)

Pin No.	Name	Туре	Description	
26	VDD_SRC_IO	PWR	IO power supply for SRC outputs.	
27	SRC4	O, DIF	100MHz Differential serial reference clocks.	
28	SRC4#	O, DIF	100MHz Differential serial reference clocks.	
29	SRC5#CPU_STP#	I/O, Dif	3.3V tolerant input for stopping CPU outputs/100MHz Differential serial reference clocks.	
30	SRC5/PCI_STP#	I/O, Dif	3.3V tolerant input for stopping PCI and SRC outputs/100MHz Differential serial reference clocks.	
31	VDD_SRC	PWR	3.3V Power supply for SRC PLL.	
32	SRC6#	O, DIF		
33	SRC6	O, DIF	100MHz Differential serial reference clocks.	
34	VSS_SRC	GND	Ground for outputs.	
35	SRC7#/OE#_6	I/O, Dif	100MHz Differential serial reference clocks/3.3V OE#6 Input controlling SRC6. (Default SRC7, 100MHz clock).	
36	SRC7/OE#_8	I/O, Dif	100MHz Differential serial reference clocks/3.3V OE#8 Input controlling SRC8. (Default SRC7, 100MHz clock).	
37	VDD_SRC_IO	PWR	0.7V power supply for SRC outputs.	
38	SRC8#/CPU2#_ITP#	O, DIF	Selectable differential CPU or SRC clock output. ITP_EN = 0 at CKPWRGD assertion = SRC8 ITP_EN = 1 @ CKPWRGD assertion = CPU2 (Note: CPU2 is an iAMT clock in iAMT mode depending on the configuration set in Byte 11 Bit3:2)	
39	SRC8/CPU2_ITP	O, DIF	F Selectable differential CPU or SRC clock output. ITP_EN = 0 at CKPWRGD assertion = SRC8 ITP_EN = 1 @ CKPWRGD assertion = CPU2 (Note: CPU2 is an iAMT clock in iAMT mode depending on the configuration set in Byte 1 Bit3:2)	
40	IO_VOUT	PWR	Integrated Linear Regulator Control.	
41	VDD_CPU_IO	PWR	IO Power supply for CPU outputs.	
42	CPU1#	O, DIF	Differential CPU clock outputs. (Note: CPU1 is an iAMT clock in iAMT mode depending on the configuration set in Byte 11 Bit3:2)	
43	CPU1	O, DIF	Differential CPU clock outputs. (Note: CPU1 is an iAMT clock in iAMT mode depending on the configuration set in Byte 11 Bit3:2)	
44	VSS_CPU	GND	Ground for outputs.	
45	CPU#0	O, DIF	Differential CPU clock outputs.	
46	CPU0	O, DIF	Differential CPU clock outputs.	
47	VDD_CPU	PWR	3.3V Power supply for CPU PLL.	
48	CKPWRGD/PD#	I	3.3V LVTTL input. This pin is a level sensitive strobe used to latch the FS_A, FS_B, FS_C, FS_D, SRC5_SEL, and ITP_EN.  After CKPWRGD (active HIGH) assertion, this pin becomes a real-time input for asserting power down (active LOW).	
49	FSB/TEST_MODE	I	3.3V tolerant input for CPU frequency selection. Selects Ref/N or Tri-state when in test mode 0 = Tri-state, 1 = Ref/N. Refer to DC Electrical Specifications table for Vil_FS and Vih_FS specifications.	
50	VSS_REF	GND	Ground for outputs.	
51	XOUT	O, SE	14.318MHz Crystal output. (Float XOUT if using CLKIN)	
52	XIN/CLKIN	I	14.318MHz Crystal input or 3.3V, 14.318MHz input clock signal.	
53	VDD_REF	PWR	3.3V Power supply for outputs and also maintains SMBUS registers during power-down.	



#### **56 TSSOP Pin Definition** (continued)

Pin No.	Name	Туре	Description
54	REF0/FSC/TEST_SEL		3.3V tolerant input for CPU frequency selection/fixed 14.318MHz clock output. Selects test mode if pulled to $V_{IHFS\_C}$ when CKPWRGD is asserted HIGH. Refer to DC Electrical Specifications table for $V_{ILFS\_C}$ , $V_{IMFS\_C}$ , $V_{IHFS\_C}$ specifications.
55	SMB_DATA	I/O	SMBus compatible SDATA.
56	SMB_CLK	I	SMBus compatible SCLOCK.

Table 1. Frequency Select Pin (FSA, FSB and FSC)

FSC	FSB	FSA	CPU	SRC	PCIF/PCI	27MHz	REF	DOT96	USB
0	0	0	266MHz						
0	0	1	133MHz						
0	1	0	200MHz						
0	1	1	166MHz	100MHz	33MHz	27MHz	14.318MHz	96MHz	48MHz
1	0	0	333MHz		00				
1	0	1	100MHz						
1	1	0	400MHz						
1	1	1	200MHz						

## Frequency Select Pin (FSA, FSB and FSC)

Apply the appropriate logic levels to FSA, FSB, and FSC inputs before CKPWRGD assertion to achieve host clock frequency selection. When the clock chip sampled HIGH on CKPWRGD and indicates that VTT voltage is stable then FSA, FSB, and FSC input values are sampled. This process employs a one-shot functionality and once the CKPWRGD sampled a valid HIGH, all other FSA, FSB, FSC, and CKPWRGD transitions are ignored except in test mode.

#### Serial Data Interface

To enhance the flexibility and function of the clock synthesizer, a two-signal serial interface is provided. Through the Serial Data Interface, various device functions, such as individual clock output buffers are individually enabled or disabled. The registers associated with the Serial Data Interface initialize to

their default setting at power-up. The use of this interface is optional. Clock device register changes are normally made at system initialization, if any are required. The interface cannot be used during system operation for power management functions.

#### **Data Protocol**

The clock driver serial protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, access the bytes in sequential order from lowest to highest (most significant bit first) with the ability to stop after any complete byte is transferred. For byte write and byte read operations, the system controller can access individually indexed bytes. The offset of the indexed byte is encoded in the command code described in *Table 2*.

The block write and block read protocol is outlined in *Table 3* while *Table 4* outlines byte write and byte read protocol. The slave receiver address is 11010010 (D2h).

**Table 2. Command Code Definition** 

Bit	Description				
7	= Block read or block write operation, 1 = Byte read or byte write operation				
(6:0)	Byte offset for byte read or byte write operation. For block read or block write operations, these bits should be '0000000'				

Table 3. Block Read and Block Write Protocol

	Block Write Protocol		Block Read Protocol
Bit	Description	Bit	Description
1	Start	1	Start
8:2	Slave address–7 bits	8:2	Slave address–7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave



**Table 3. Block Read and Block Write Protocol** (continued)

	Block Write Protocol		Block Read Protocol		
Bit	Description	Bit	Description		
18:11	Command Code–8 bits	18:11	Command Code–8 bits		
19	Acknowledge from slave	19	Acknowledge from slave		
27:20	Byte Count–8 bits	20	Repeat start		
28	Acknowledge from slave	27:21	Slave address–7 bits		
36:29	Data byte 1–8 bits	28	Read = 1		
37	Acknowledge from slave	29	Acknowledge from slave		
45:38	Data byte 2–8 bits	37:30	Byte Count from slave–8 bits		
46	Acknowledge from slave	38	Acknowledge		
	Data Byte /Slave Acknowledges	46:39	Data byte 1 from slave–8 bits		
	Data Byte N–8 bits	47	Acknowledge		
	Acknowledge from slave	55:48	Data byte 2 from slave–8 bits		
	Stop	56	Acknowledge		
			Data bytes from slave / Acknowledge		
			Data Byte N from slave–8 bits		
			NOT Acknowledge		
			Stop		

**Table 4. Byte Read and Byte Write Protocol** 

	Byte Write Protocol		Byte Read Protocol
Bit	Description	Bit	Description
1	Start	1	Start
8:2	Slave address–7 bits	8:2	Slave address–7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave
18:11	Command Code–8 bits	18:11	Command Code–8 bits
19	Acknowledge from slave	19	Acknowledge from slave
27:20	Data byte–8 bits	20	Repeated start
28	Acknowledge from slave	27:21	Slave address–7 bits
29	Stop	28	Read
		29	Acknowledge from slave
		37:30	Data from slave–8 bits
		38	NOT Acknowledge
		39	Stop



# **Control Registers**

## Byte 0: Control Register 0

Bit	@Pup	Name	Description	
7	HW	FS_C	CPU Frequency Select Bit, set by HW	
6	HW	FS_B	CPU Frequency Select Bit, set by HW	
5	HW	FS_A	CPU Frequency Select Bit, set by HW	
4	0	iAMT_EN	Set via SMBus or by combination of PWRDWN, CPU_STP, and PCI_STP 0 = Legacy Mode, 1 = iAMT Enabled, Sticky 1	
3	0	RESERVED	RESERVED	
2	0	SRC_MAIN_SEL	Select source for SRC clock,  0 = SRC_MAIN = PLL1, PLL3_CFB Table applies  1 = SRC_MAIN = PLL3, PLL3_CFB Table does not apply	
1	0	SATA_SEL	Select source of SATA clock 0 = SATA SRC_MAIN, 1= SATA PLL2	
0	1	PD_Restore	Save Config. In powerdown 0 = Config. Cleared, 1 = Config. Saved	

## Byte 1: Control Register 1

Bit	@Pup	Name	Description		
7	0	SRC0_SEL	Select for SRC0 or DOT96, 0 = SRC0, 1 = DOT96		
6	0	PLL1_SS_DC	Select for down or center SS, 0 = Down spread, 1 = Center spread		
5	0	PLL3_SS_DC	Select for down or center SS, 0 = Down spread, 1 = Center spre	ad	
4	0	PLL3_CFB3	Bit 4:1 only apply when SRC_SEL	=0	
3	0	PLL3_CFB2	0000 = PLL3 Disable Default	PLL3 OFF, SRC1 = SRC_MAIN	
2	0	PLL3_CFB1	0001 = 100 MHz 0.5% SSC Stby	PLL3 ON, SRC1 = SRC_MAIN	
1	1	PLL3_CFB0	config to HW mode 3) 1110 = RESERVED 1111 = RESERVED	4B (98.304M) on SE2 SE2 Disabled (set whenPCl3/CFB0 is set high to	
0	1	PCI_SEL	Select PCI Clock source from PLL 0 = PLL1, 1 = SRC_MAIN	1 or SRC_MAIN	

# Byte 2: Control Register 2

Bit	@Pup	Name	Description	
7	1		Output enable for REF 0 = Output Disabled, 1 = Output Enabled	
6	1	_	Output enable for USB 0 = Output Disabled, 1 = Output Enabled	



## Byte 2: Control Register 2 (continued)

Bit	@Pup	Name	Description
5	1	PCIF0_OE	Output enable for PCIF0 0 = Output Disabled, 1 = Output Enabled
4	1	PCI4_OE	Output enable for PCI4 0 = Output Disabled, 1 = Output Enabled
3	1	PCI3_OE	Output enable for PCI3 0 = Output Disabled, 1 = Output Enabled
2	1	PCI2_OE	Output enable for PCI2 0 = Output Disabled, 1 = Output Enabled
1	1	PCI1_OE	Output enable for PCI1 0 = Output Disabled, 1 = Output Enabled
0	1	PCI0_OE	Output enable for PCI0 0 = Output Disabled, 1 = Output Enabled

## Byte 3: Control Register 3

Bit	@Pup	Name	Description
7	1	RESERVED	RESERVED
6	1	RESERVED	RESERVED
5	1	RESERVED	RESERVED
4	1	SRC8/ITP_OE	Output enable for SRC8 or ITP, 0 = Output Disabled, 1 = Output Enabled
3	1	SRC7_OE	Output enable for SRC7 0 = Output Disabled, 1 = Output Enabled
2	1	SRC6_OE	Output enable for SRC6 0 = Output Disabled, 1 = Output Enabled
1	1	SRC5_OE	Output enable for SRC5 0 = Output Disabled, 1 = Output Enabled
0	1	SRC4_OE	Output enable for SRC4 0 = Output Disabled, 1 = Output Enabled

## Byte 4: Control Register 4

Bit	@Pup	Name	Description
7	1	SRC3_OE	Output enable for SRC3 0 = Output Disabled, 1 = Output Enabled
6	1	SRC2/SATA_OE	Output enable for SATA/SRC2 0 = Output Disabled, 1 = Output Enabled
5	1	SRC1_OE	Output enable for SRC 0 = Output Disabled, 1 = Output Enabled
4	1	SRC0/DOT96_OE	Output enable for SRC0/DOT96 0 = Output Disabled, 1 = Output Enabled
3	1	CPU1_OE	Output enable for CPU1 0 = Output Disabled, 1 = Output Enabled
2	1	CPU0_OE	Output enable for CPU0 0 = Output Disabled, 1 = Output Enabled
1	1	PLL1_SS_EN	Enable PLL1's spread modulation, 0 = Spread Disabled 1 = Spread Enabled
0	1	PLL3_SS_EN	Enable PLL3's spread modulation 0 = Spread Disabled, 1 = Spread Enabled



## Byte 5: Control Register 5

Bit	@Pup	Name	Description
7	0	OE#_0/2_EN_A	Enable OE#_0/2 (clk req) 0 = Disabled OE#_0/2, 1 = Enabled OE#_0/2,
6	0	OE#_0/2_SEL_A	Set OE#_0/2 $\rightarrow$ SRC0 or SRC2 0 = OE#_0/2 $\rightarrow$ SRC0, 1 = OE#_0/2 $\rightarrow$ SRC2
5	0	OE#_1/4_EN_A	Enable OE#_1/4 (clk req) 0 = Disabled OE#_1/4, 1 = Enabled OE#_1/4,
4	0	OE#_1/4_SEL_A	Set OE#_1/4 $\rightarrow$ SRC1 or SRC4 0 = OE#_1/4 $\rightarrow$ SRC1, 1 = OE#_1/4 $\rightarrow$ SRC4
3	0	OE#_0/2_EN_B	Enable OE#_0/2 (clk req) 0 = Disabled OE#_0/2 1 = Enabled OE#_0/2
2	0	OE#_0/2_SEL_B	Set $OE\#_0/2 \rightarrow SRC0$ or $SRC2$ 0 = $OE\#_0/2 \rightarrow SRC0$ , 1 = $OE\#_0/2 \rightarrow SRC2$
1	0	OE#_1/4_EN_B	Enable OE#_1/4 (clk req) 0 = Disabled OE#_1/4, 1 = Enabled OE#_1/4,
0	0	OE#_1/4_SEL_B	Set OE#_1/4 $\rightarrow$ SRC1 or SRC4 0 = OE#_1/4 $\rightarrow$ SRC1, 1 = OE#_1/4 $\rightarrow$ SRC4

# Byte 6: Control Register 6

Bit	@Pup	Name	Description
7	0	OE#_6_EN	Enable OE#_6 (clk req) → SRC6
6	0	OE#_8_EN	Enable OE#_8 (clk req) → SRC8
5	0	OE#_9_EN	Enable OE#_9 (clk req) → SRC9
4	0	OE#_10_EN	Enable OE#_10 (clk req) → SRC10
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	0	LCD_100_STP_CTRL	Allows control of LCD_100 with assertion of PCI_STP# 0 = Free runningLCD_100, 1 = Stopped with PCI_STP#
0	0	SRC_STP_CTRL	Allows control of SRC with assertion of PCI_STP#  0 = Free running SRC 1 = Stopped with PCI_STP#

## Byte 7: Vendor ID

Bit	@Pup	Name	Description
7	0	Rev Code Bit 3	Revision Code Bit 3
6	0	Rev Code Bit 2	Revision Code Bit 2
5	0	Rev Code Bit 1	Revision Code Bit 1
4	1	Rev Code Bit 0	Revision Code Bit 0
3	1	Vendor ID bit 3	Vendor ID Bit 3
2	0	Vendor ID bit 2	Vendor ID Bit 2
1	0	Vendor ID bit 1	Vendor ID Bit 1
0	0	Vendor ID bit 0	Vendor ID Bit 0



## Byte 8: Control Register 8

Bit	@Pup	Name	Description
7	0	Device_ID3	0000 = CK505 Yellow Cover Device, 56-pin TSSOP
6	0	Device_ID2	10001 = CK505 Yellow Cover Device, 64-pin TSSOP   10010 = CK505 Yellow Cover Device, 48-pin QFN (reserved)
5	0	Device_ID1	0011 = CK505 Yellow Cover Device, 56-pin QFN (reserved)
4	0	Device_ID0	0100 = CK505 Yellow Cover Device, 64-pin QFN (reserved) 0101 = CK505 Yellow Cover Device, 72-pin QFN (reserved) 0110 = CK505 Yellow Cover Device, 48-pin SSOP (reserved) 0111 = CK505 Yellow Cover Device, 56-pin SSOP (reserved) 1000 = Reserved 1001 = Reserved 1010 = Reserved 1011 = Reserved 1100 = Reserved 1101 = Reserved 1110 = Reserved 1111 = Reserved
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	0	SE1_OE	SE1 Output enable 0 = Output Disabled, 1 = Output Enabled
0	0	SE2_OE	SE2 Output enable 0 = Output Disabled, 1 = Output Enabled

## Byte 9: Control Register 9

Bit	@Pup	Name	Description
7	0	PCIF0_STP_CTRL	Allows control of PCIF0 with assertion of PCI_STP#  0 = Free running PCIF, 1 = Stopped with PCI_STP#
6	HW	TME_STRAP	Trusted mode enable strap status, 0 = normal, 1 = no overclocking
5	1	REF_Bit1	REF drive strength control, See Byte 18 for more setting 0 = Low, 1 = High
4	0	TEST_MODE_SEL	Mode select either REF/N or tri-state 0 = All output tri-state, 1 = All output REF/N
3	0	TEST_MODE_ENTRY	Allow entry into test mode 0=Normal operation, 1=Enter test mode
2	1	IO_VOUT2	IO_VOUT[2,1,0]
1	0	IO_VOUT1	000 = 0.3V
0	1	IO_VOUT0	

## Byte 10: Control Register 10

Bit	@Pup	Name	Description
7	HW	SRC5_EN_STRAP	Read only bit for SRC5_EN_STRAP  0 = CPU/PCI_STP enabled, 1 = SRC5 pair enabled
6	1	PLL3_EN	PLL3 Enabled 0 = PLL3 disabled, 1 = PLL3 enabled
5	1	PLL2_EN	PLL2 Enabled 0 = PLL2 disabled, 1 = PLL2 enabled
4	1	SRC_DIV_EN	SRC Divider Enabled 0 = SRC Divider disabled, 1 = SRC Divider enabled



Byte 10: Control Register 10 (continued)

Bit	@Pup	Name	Description
3	1	PCI_DIV_EN	PCI Divider Enabled 0 = PCI Divider disabled, 1 = PCI Divider enabled
2	1	CPU_DIV_EN	CPU Divider Enabled 0 = CPU Divider disabled, 1 = CPU Divider enabled
1	1	CPU1_STP_CRTL	Allow control of CPU1 with assertion of CPU_STP# 0 = Free running, 1 = Stopped with CPU_STP#
0	1	CPU0_STP_CRTL	Allow control of CPU0 with assertion of CPU_STP# 0 = Free running, 1 = Stopped with CPU_STP#

## Byte 11: Control Register 11

Bit	@Pup	Name	Description
7	HW	PCI3 CEG1	
		PCI3_CFG1	
6	HW	PCI3_CFG0	CFG PCI2/T PCI3/ PLL1 PLL2 PLL3
			[1:0] ME CGF0 Mode Output SSC Output SSC Output SSC
			00 x Low 0-Def CPU/SRC/PCl33 Down USB NA
			01 x Mid 1 CPU Down USB NA SRC/PCI33 Down
			10 0 High 2 CPU Center USB NA SRC/PCI33 Down
			11 1 High 3 CPU Center USB/25M NA SRC/PCl33 Down
5	0	25MHz_EN_SE1	25MHz Output Enabled applies to Powerdown / M1 (Only applies when PCI3/CGFG0 strap is set high to enter HW mode 3) 0 = 25MHz disabled in Powerdown / M1 1 = 25MHz enabled in Powerdown / M1; Sticky 1
4	1	RESERVED	RESERVED
3	0	CPU2_AMT_EN	
2	1	CPU1_AMT_EN	PCIF0/ITP_EN AMT_EN CPU2_AMT_EN CPU1_AMT_EN Description
			x 1 0 0 Reserved
			x 1 0 1 CPU1 = M1 Clock
			1 1 1 0 CPU2 - M1 Clock
			1 1 1 1 CPU1 and CPU2 = M1 Clock
1	1	PCI-E_GEN2	PCI-E_Gen2 Compliant (Read Only bit)
			0 = non Gen2, 1= Gen2 Compliant
0	1	CPU2_STP_CRTL	Allow control of CPU2 with assertion of CPU_STP# 0 = Free running, 1 = Stopped with CPU_STP#

## Byte 12: Byte Count

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	0	BC5	Byte count
4	0	BC4	Byte count
3	1	BC3	Byte count
2	1	BC2	Byte count
1	0	BC1	Byte count
0	1	BC0	Byte count



Byte 13: Control Register 13

Bit	@Pup	Name	Description
7	1	USB_Bit1	USB drive strength control, See Byte 18 for more setting 0 = Low, 1= High
6	1	PCI/PCIF_Bit1	PCI drive strength control, See Byte 18 for more setting 0 = Low, 1 = High
5	0	PLL1_Spread	Select percentage of spread for PLL1 0 = 0.5%, 1=0.45%
4	0	SATA_SS_EN	Enable SATA spread modulation, 0 = Spread Disabled 1 = Spread Enabled
3	1	EN_CFG0_SET	By defalult CFG0 pin strap sets the SMBus initial values to select the HW mode. When this bit is written0, subsequent SMBus accesses is the Lathes Open state, can overwrite the CFG0 pin setting into the SMBus bits and set the mode before the M0 state: specifically B0b2, B1b[6,4,3], B9b1, B11b5
2	1	SE1/SE2_Bit1	SE1 and SE2 drive strength control, See Byte 18 for more setting 0 = Low, 1 = High
1	1	RESERVED	RESERVED
0	1	SW_PCI	SW PCI_STP# Function 0 = SW PCI_STP assert, 1 = SW PCI_STP deassert When this bit is set to 0, all STOPPABLE PCI, PCIF and SRC outputs will be stopped in a synchronous manner with no short pulses. When this bit is set to 1, all STOPPED PCI, PCIF and SRC outputs will resume in a synchronous manner with no short pulses.

## Byte 14: Control Register 14

Bit	@Pup	Name	Description
7	0	CPU_DAF_N7	If Prog_CPU_EN is set, the values programmed in CPU_DAF_N[8:0] and
6	0	CPU_DAF_N6	CPU_DAF_M[6:0] will be used to determine the CPU output frequency. The setting of the FS_Override bit determines the frequency ratio for CPU and
5	0	CPU_DAF_N5	other output clocks. When it is cleared, the same frequency ratio stated in
4	0	CPU_DAF_N4	the Latched FS[C:A] register will be used. When it is set, the frequency ratio stated in the FSEL[2:0] register will be used
3	0	CPU_DAF_N3	Stated III the FSEL[2.0] register will be used
2	0	CPU_DAF_N2	
1	0	CPU_DAF_N1	
0	0	CPU_DAF_N0	

## Byte 15: Control Register 15

Bit	@Pup	Name	Description			
7	0	CPU_DAF_N8	See Byte 14 for description			
6	0	CPU_DAF_M6	If Prog_CPU_EN is set, the values programmed are in CPU_FSEL_N[8:0]			
5	0	CPU_DAF_M5	and CPU_FSEL_M[6:0] will be used to determine the CPU output frequency. The setting of the FS_Override bit determines the frequency			
4	0	CPU_DAF_M4	ratio for CPU and other output clocks. When it is cleared, the same			
3	0	CPU_DAF_M3	Take for or or and other ordered. When he ordered, the other			
2	0	CPU_DAF_M2	Is set, the frequency fatto stated in the FSEL[2.0] register will be used			
1	0	CPU_DAF_M1				
0	0	CPU_DAF_M0				

## Byte 16: Control Register 16

Bit	@Pup	Name	Description
-----	------	------	-------------



## Byte 16: Control Register 16

7	0		If Prog_SRC_EN is set, the values programmed in SRC_DAF_N[7:0] will
6	0	PCI-E_N6	be used to determine the SRC output frequency.
5	0	PCI-E_N5	
4	0	PCI-E_N4	
3	0	PCI-E_N3	
2	0	PCI-E_N2	
1	0	PCI-E_N1	
0	0	PCI-E_N0	

## Byte 17: Control Register 17

Bit	@Pup	Name	Description
7	0	SMSW_EN	Enable Smooth Switching, 0 = Disabled, 1= Enabled
6	0	SMSW_SEL	Smooth switch select, 0 = CPU_PLL, 1 = SRC_PLL
5	0	RESERVED	RESERVED
4	0	Prog_PCI-E_EN	Programmable PCI-E frequency enable 0 = Disabled, 1= Enabled
3	0	Prog_CPU_EN	Programmable CPU frequency enable 0 = Disabled, 1= Enabled
2	0	RESERVED	RESERVED
1	0	RESERVED	RESERVED
0	0	RESERVED	RESERVED

## Byte 18: Control Register 18

Bit	@Pup	Name	Description				
7	0	PCIF/PCI_Bit2	Drive Strength Cor	ntrol - Bit[2:0]			
6	1	PCIF/PCI_Bit0		Bit 2	Bit 1	Bit 0	Buffer
5	0	USB_Bit2		(Byte18)	(Various Bytes)	(Byte 18)	Strength
4	0	USB_Bit0		1	1	1	Strongest
3	0	SE1/SE2_Bit2		1	1	0	♠
2	0	SE1/SE2_Bit0		1	0	1	
1	0	REF_Bit2		1	0	0	
	, ,		Default PCI	0	1	1	
0	0	REF_Bit0	Default REF/Usb	0	1	0	
				0	0	1	<b>'</b>
				0	0	0	Weakest
i			-				

## Table 5. Output Driver Status during PCI-STP# and CPU-STP#

		PCI_STP# Asserted	CPU_STP# Asserted	SMBus OE Disabled
Single-ended Clocks	Stoppable	Driven low	Running	Driven low
	Non stoppable	Running	Running	
Differential Clocks	Stoppable	Clock driven high	Clock driven high	Clock driven Low or 20K
		Clock# driven low	Clock# driven low	pulldown
	Non stoppable	Running	Running	-

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**Table 6. Output Driver Status** 

	All Single-ended Clocks		All Differential Cl CPU1		CPU1	
	w/o Strap	w/ Strap	Clock	Clock#	Clock	Clock#
Latches Open State	Low	Hi-z	Low or 20K pulldown	Low	Low or 20K pulldown	Low
Powerdown	Low	Hi-z	Low or 20K pulldown	Low	Low or 20K pulldown	Low
M1	Low	Hi-z	Low or 20K pulldown	Low	Running	Running

**Table 7. Crystal Recommendations** 

Frequency (Fund)	Cut	Loading	Load Cap	Drive (max.)	Shunt Cap (max.)	Motional (max.)	Tolerance (max.)	Stability (max.)	Aging (max.)
14.31818 MHz	AT	Parallel	20 pF	0.1 mW	5 pF	0.016 pF	35 ppm	30 ppm	5 ppm

The SL28506-2 requires a Parallel Resonance Crystal. Substituting a series resonance crystal causes the SL28506-2 to operate at the wrong frequency and violates the ppm specification. For most applications there is a 300-ppm frequency shift between series and parallel crystals due to incorrect loading.

### **Crystal Loading**

Crystal loading plays a critical role in achieving low ppm performance. To realize low ppm performance, use the total capacitance the crystal sees to calculate the appropriate capacitive loading (CL).

Figure 1 shows a typical crystal configuration using the two trim capacitors. It is important that the trim capacitors are in series with the crystal. It is not true that load capacitors are in parallel with the crystal and are approximately equal to the load capacitance of the crystal.

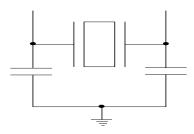


Figure 1. Crystal Capacitive Clarification

#### **Calculating Load Capacitors**

In addition to the standard external trim capacitors, consider the trace capacitance and pin capacitance to calculate the crystal loading correctly. Again, the capacitance on each side is in series with the crystal. The total capacitance on both side is twice the specified crystal load capacitance (CL). Trim capacitors are calculated to provide equal capacitive loading on both sides.

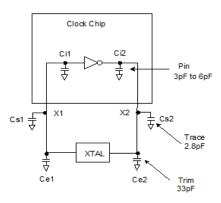


Figure 2. Crystal Loading Example

Use the following formulas to calculate the trim capacitor values for Ce1 and Ce2.

#### Load Capacitance (each side)

$$Ce = 2 * CL - (Cs + Ci)$$

Total Capacitance (as seen by the crystal)

CLe = 
$$\frac{1}{\left(\frac{1}{\text{Ce1} + \text{Cs1} + \text{Ci1}} + \frac{1}{\text{Ce2} + \text{Cs2} + \text{Ci2}}\right)}$$

# Dial-A-Frequency® (CPU and SRC)

This feature allows the user to over-clock their system by slowly stepping up the CPU or SRC frequency. When the programmable output frequency feature is enabled, the CPU and SRC frequencies are determined by the following equation:



Fcpu = G \* N/M or Fcpu=G2 \* N, where G2 = G/M.

- "N" and "M" are the values programmed in Programmable Frequency Select N-Value Register and M-Value Register, respectively.
- "G" stands for the PLL Gear Constant, which is determined by the programmed value of FS[E:A]. See *Table 1*, *Frequency Select Table* for the Gear Constant for each Frequency selection. The PCI Express only allows user control of the N register, the M value is fixed and documented in *Table 1*, *Frequency Select Table*.

In this mode, the user writes the desired N and M values into the DAF I2C registers. The user cannot change only the M value and must change both the M and the N values at the same time, if they require a change to the M value. The user may change only the N value.

#### **Associated Register Bits**

- CPU\_DAF Enable This bit enables CPU DAF mode. By default, it is not set. When set, the operating frequency is determined by the values entered into the CPU\_DAF\_N register. Note that the CPU\_DAF\_N and M register must contain valid values before CPU\_DAF is set. Default = 0, (No DAF).
- CPU\_DAF\_N There are nine bits (for 512 values) to linearly change the CPU frequency (limited by VCO range).
   Default = 0, (0000). The allowable values for N are detailed in Table 1, Frequency Select Table.
- CPU DAF M There are 7 bits (for 128 values) to linearly change the CPU frequency (limited by VCO range). Default = 0, the allowable values for M are detailed in Table 1, Frequency Select Table
- SRC\_DAF Enable This bit enables SRC DAF mode. By default, it is not set. When set, the operating frequency is determined by the values entered into the SRC\_DAF\_N register. Note that the SRC\_DAF\_N register must contain valid values before SRC\_DAF is set. Default = 0, (No DAF).
- SRC\_DAF\_N There are nine bits (for 512 values) to linearly change the CPU frequency (limited by VCO range).
   Default = 0, (0000). The allowable values for N are detailed in Table 1, Frequency Select Table.

#### Smooth Switching

The device contains one smooth switch circuit that is shared by the CPU PLL and SRC PLL. The smooth switch circuit ensures that when the output frequency changes by overclocking, the transition from the old frequency to the new frequency is a slow, smooth transition containing no glitches. The rate of change of output frequency when using the smooth switch circuit is less than 1 MHz/0.667  $\mu s$ . The frequency overshoot and undershoot is less than 2%.

The Smooth Switch circuit assigns auto or manual. In Auto mode, clock generator assigns smooth switch automatically when the PLL does overclocking. For manual mode, assign the smooth switch circuit to PLL via Smbus. By default the smooth switch circuit is set to auto mode. PLL can be over-clocked when it does not have control of the smooth switch circuit but it is not guaranteed to transition to the new frequency without large frequency glitches.

Do not enable over-clocking and change the N values of both PLLs in the same SMBUS block write and use smooth switch mechanism on spread spectrum on/off.

#### PD RESTORE

If a '0' is set for Byte 0 bit 0 then, upon assertion of PD# LOW, the SL28506-2 initiates a full reset. The result of this is that the clock chip emulates a cold power on start and goes to the "Latches Open" state. If the PD\_RESTORE bit is set to a '1' then the configuration is stored upon PD# asserted LOW. Note that if the iAMT bit, Byte 0 bit 3, is set to a '1' then the PD\_RESTORE bit must be ignored. In other words, in Intel iAMT mode, PD# reset is not allowed.

#### PD# (Power down) Clarification

The CKPWRGD/PD# pin is a dual-function pin. During initial power up, the pin functions as CKPWRGD. Once CKPWRGD has been sampled HIGH by the clock chip, the pin assumes PD# functionality. The PD# pin is an asynchronous active LOW input used to shut off all clocks cleanly before shutting off power to the device. This signal is synchronized internally to the device before powering down the clock synthesizer. PD# is also an asynchronous input for powering up the system. When PD# is asserted LOW, clocks are driven to a LOW value and held before turning off the VCOs and the crystal oscillator.

#### PD# (Power down) Assertion

When PD is sampled HIGH by two consecutive rising edges of CPUC, all single-ended outputs will be held LOW on their next HIGH-to-LOW transition and differential clocks must held LOW. When PD mode is desired as the initial power on state, PD must be asserted HIGH in less than 10  $\mu s$  after asserting CKPWRGD.

#### **PD# Deassertion**

The power up latency is less than 1.8 ms. This is the time from the deassertion of the PD# pin or the ramping of the power supply until the time that stable clocks are generated from the clock chip. All differential outputs stopped in a three-state condition, resulting from power down are driven high in less than 300  $\mu s$  of PD# deassertion to a voltage greater than 200 mV. After the clock chip's internal PLL is powered up and locked, all outputs are enabled within a few clock cycles of each clock. Figure 4 is an example showing the relationship of clocks coming up.



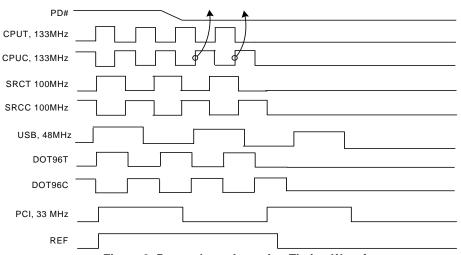


Figure 3. Power down Assertion Timing Waveform

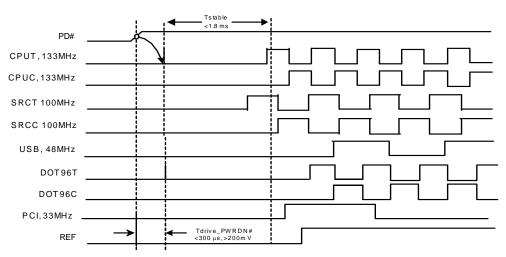


Figure 4. Power down Deassertion Timing Waveform

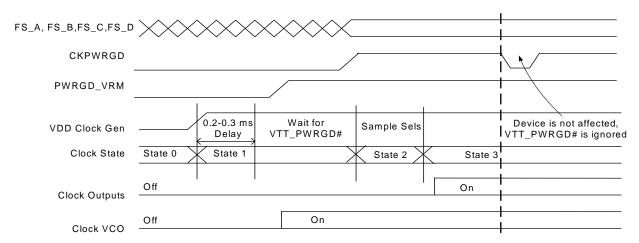


Figure 5. CKPWRGD Timing Diagram



#### **CPU STP# Assertion**

The CPU\_STP# signal is an active LOW input used for synchronous stopping and starting the CPU output clocks while the rest of the clock generator continues to function. When the CPU\_STP# pin is asserted, all CPU outputs that are set with the SMBus configuration to be stoppable are stopped within two to six CPU clock periods after sampled by two rising edges of the internal CPUC clock. The final states of the stopped CPU signals are CPUT = HIGH and CPUC = LOW.

#### **CPU STP# Deassertion**

The deassertion of the CPU\_STP# signal causes all stopped CPU outputs to resume normal operation in a synchronous manner. No short or stretched clock pulses are produced when the clock resumes. The maximum latency from the deassertion to active outputs is no more than two CPU clock cycles.

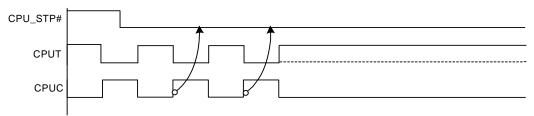


Figure 6. CPU\_STP# Assertion Waveform

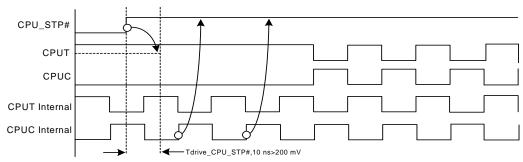


Figure 7. CPU\_STP# Deassertion Waveform

#### PCI\_STP# Assertion

The PCI\_STP# signal is an active LOW input used for synchronously stopping and starting the PCI outputs while the rest of the clock generator continues to function. The set-up time for capturing PCI\_STP# going LOW is 10 ns (t<sub>SU</sub>). (See *Figure 8.*) The PCIF clocks are affected by this pin if their corresponding control bit in the SMBus register is set to allow them to be free running.

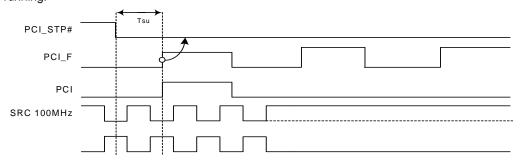


Figure 8. PCI\_STP# Assertion Waveform



#### **PCI STP# Deassertion**

The deassertion of the PCI\_STP# signal causes all PCI and stoppable PCIF clocks to resume running in a synchronous manner within two PCI clock periods, after PCI\_STP# transitions to a HIGH level.

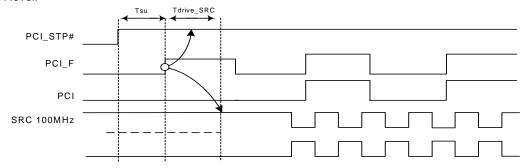


Figure 9. PCI\_STP# Deassertion Waveform

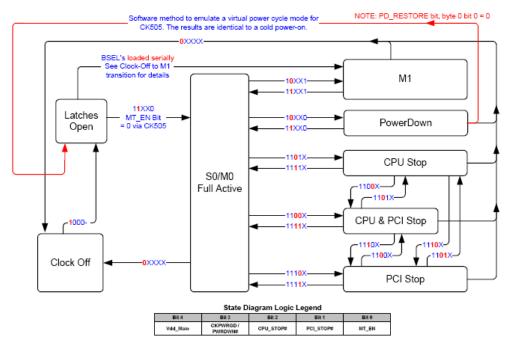


Figure 10. Clock Generator Power up/Run State Diagram



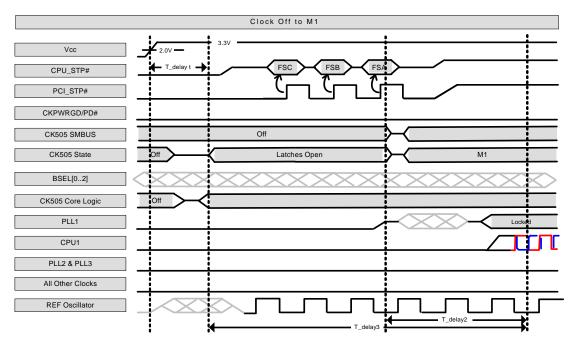


Figure 11. BSEL Serial Latching

#### **Absolute Maximum Conditions**

Parameter	Description	Condition	Min.	Max.	Unit
$V_{DD\_3.3V}$	Supply Voltage	Functional	_	4.6	V
$V_{DD\_IO}$	IO Supply Voltage	Functional		1.5	V
V <sub>IN</sub>	Input Voltage	Relative to V <sub>SS</sub>	-0.5	4.6	$V_{DC}$
T <sub>S</sub>	Temperature, Storage	Non-functional	-65	150	°C
T <sub>A</sub>	Commercial Temperature, Operating Ambient	Functional	0	85	°C
	Industrial Temperature, Operating Ambient		-40	+85	°C
TJ	Temperature, Junction	Functional	_	150	°C
Ø <sub>JC</sub>	Dissipation, Junction to Case	JEDEC (JESD 51)	-	20	°C/W
Ø <sub>JA</sub>	Dissipation, Junction to Ambient	JEDEC (JESD 51)	-	60	°C/ W
ESD <sub>HBM</sub>	ESD Protection (Human Body Model)	JEDEC (JESD 22-A114)	2000	_	V
UL-94	Flammability Rating	UL (CLASS)	V-	V-0	
MSL	Moisture Sensitivity Level		1	1	

Multiple Supplies: The Voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is NOT required.



# **DC Electrical Specifications**

Parameter	Description	Condition	Min.	Max.	Unit
VDD core	3.3V Operating Voltage	3.3 ± 5%	3.135	3.465	V
V <sub>IH</sub>	3.3V Input High Voltage (SE)		2.0	$V_{DD} + 0.3$	V
V <sub>IL</sub>	3.3V Input Low Voltage (SE)		$V_{SS} - 0.3$	0.8	V
V <sub>IHI2C</sub>	Input High Voltage	SDATA, SCLK	2.2	_	V
V <sub>ILI2C</sub>	Input Low Voltage	SDATA, SCLK	_	1.0	V
V <sub>IH_FS</sub>	FS_[A,B] Input High Voltage		0.7	1.5	V
V <sub>IL_FS</sub>	FS_[A,B] Input Low Voltage		$V_{SS} - 0.3$	0.35	V
V <sub>IHFS_C_TEST</sub>	FS_C Input High Voltage		2	$V_{DD} + 0.3$	V
V <sub>IMFS_C_NORMAL</sub>	FS_C Input Middle Voltage		0.7	1.5	V
V <sub>ILFS_C_NORMAL</sub>	FS_C Input Low Voltage		$V_{SS} - 0.3$	0.35	V
PCI3/CFG0_HIGH	PCI3/CFG0 Input High Voltage	Typ. 2.75V	2.40	VDD	V
PCI3/CFG0_MID	PCI3/CFG0 Input Mid Voltage	Typ. 1.65V	1.30	2.00	V
PCI3/CFG0_LOW	PCI3/CFG0 Input Low Voltage	Typ. 0.550V	0	0.900	V
I <sub>IH</sub>	Input High Leakage Current	Except internal pull-down resistors, $0 < V_{IN} < V_{DD}$	_	5	μА
I <sub>IL</sub>	Input Low Leakage Current	Except internal pull-up resistors, 0 < V <sub>IN</sub> < V <sub>DD</sub>	<b>-</b> 5	_	μА
V <sub>OH</sub>	3.3V Output High Voltage (SE)	$I_{OH} = -1 \text{ mA}$	2.4	_	V
$V_{OL}$	3.3V Output Low Voltage (SE)	I <sub>OL</sub> = 1 mA	_	0.4	V
V <sub>DD IO</sub>	Low Voltage IO Supply Voltage		1	1.5	V
I <sub>OZ</sub>	High-impedance Output Current		-10	10	μА
C <sub>IN</sub>	Input Pin Capacitance		1.5	5	pF
C <sub>OUT</sub>	Output Pin Capacitance			6	pF
L <sub>IN</sub>	Pin Inductance		_	7	nΗ
$V_{XIH}$	Xin High Voltage		0.7V <sub>DD</sub>	$V_{DD}$	V
$V_{XIL}$	Xin Low Voltage		0	0.3V <sub>DD</sub>	V
IDD <sub>PWRDWN</sub>	Power Down Current			1	mA
I <sub>DD3.3V</sub>	Dynamic Supply Current		_	250	mΑ

# **AC Electrical Specifications**

Parameter	Description	Condition	Min.	Max.	Unit
Crystal				•	
L <sub>ACC</sub>	Long-term Accuracy		_	300	ppm
Clock Input					
T <sub>DC</sub>	CLKIN Duty Cycle	Measured at VDD/2	47	53	%
T <sub>R</sub> /T <sub>F</sub>	CLKIN Rise and Fall Times	Measured between 0.2V <sub>DD</sub> and 0.8V <sub>DD</sub>	0.5	4.0	V/ns
T <sub>CCJ</sub>	CLKIN Cycle to Cycle Jitter	Measured at VDD/2	_	250	ps
T <sub>LTJ</sub>	CLKIN Long Term Jitter	Measured at VDD/2	_	350	ps
V <sub>IL</sub>	Input Low Voltage	XIN / CLKIN pin	_	0.8	V
V <sub>IH</sub>	Input High Voltage	XIN / CLKIN pin	2	VDD+0.3	V
I <sub>IL</sub>	Input LowCurrent	XIN / CLKIN pin, 0 < VIN <0.8	_	20	uA
I <sub>IH</sub>	Input HighCurrent	XIN / CLKIN pin, VIN = VDD	_	35	uA
CPU at 0.7V	•	<u> </u>		•	
T <sub>DC</sub>	CPU Clock Duty Cycle	Measured at 0V differential at 0.1s	45	55	%

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# AC Electrical Specifications (continued)

Parameter	Description	Condition	Min.	Max.	Unit
T <sub>PERIOD</sub>	100 MHz CPU Clock Period	Measured at 0V differential at 0.1s	9.99900	10.00100	ns
T <sub>PERIOD</sub>	133 MHz CPU Clock Period	Measured at 0V differential at 0.1s	7.49925	7.50075	ns
T <sub>PERIOD</sub>	166 MHz CPU Clock Period	Measured at 0V differential at 0.1s	5.99940	6.00060	ns
T <sub>PERIOD</sub>	200 MHz CPU Clock Period	Measured at 0V differential at 0.1s	4.99950	5.00050	ns
T <sub>PERIOD</sub>	266 MHz CPU Clock Period	Measured at 0V differential at 0.1s	3.74963	3.75038	ns
T <sub>PERIOD</sub>	333 MHz CPU Clock Period	Measured at 0V differential at 0.1s	2.99970	3.00030	ns
T <sub>PERIOD</sub>	400 MHz CPU Clock Period	Measured at 0V differential at 0.1s	2.49975	2.50025	ns
T <sub>PERIODSS</sub>	100 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	10.02406	10.02607	ns
T <sub>PERIODSS</sub>	133 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	7.51804	7.51955	ns
T <sub>PERIODSS</sub>	166 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	6.01444	6.01564	ns
T <sub>PERIODSS</sub>	200 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	5.01203	5.01303	ns
T <sub>PERIODSS</sub>	266 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	3.75902	3.75978	ns
T <sub>PERIODSS</sub>	333 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	3.00722	3.00782	ns
T <sub>PERIODSS</sub>	400 MHz CPU Clock Period, SSC	Measured at 0V differential at 0.1s	2.50601	2.50652	ns
T <sub>PERIODAbs</sub>	100 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	9.91400	10.0860	ns
T <sub>PERIODAbs</sub>	133 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	7.41425	7.58575	ns
T <sub>PERIODAbs</sub>	166 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	5.91440	6.08560	ns
T <sub>PERIODAbs</sub>	200 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	4.91450	5.08550	ns
T <sub>PERIODAbs</sub>	266 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	3.66463	3.83538	ns
T <sub>PERIODAbs</sub>	333 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	2.91470	3.08530	ns
T <sub>PERIODAbs</sub>	400 MHz CPU Clock Absolute period	Measured at 0V differential at 1 clock	2.41475	2.58525	ns
T <sub>PERIODSSAbs</sub>	100 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	9.91406	10.1362	ns
T <sub>PERIODSSAbs</sub>	133 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	7.41430	7.62340	ns
T <sub>PERIODSSAbs</sub>	166 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	5.91444	6.11572	ns
T <sub>PERIODSSAbs</sub>	200 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	4.91453	5.11060	ns
T <sub>PERIODSSAbs</sub>	266 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	3.66465	3.85420	ns
T <sub>PERIODSSAbs</sub>	333 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	2.91472	3.10036	ns
T <sub>PERIODSSAbs</sub>	400 MHz CPU Clock Absolute period, SSC	Measured at 0V differential at 1 clock	2.41477	2.59780	ns
T <sub>CCJ</sub>	CPU Cycle to Cycle Jitter	Measured at 0V differential	-	85	ps
T <sub>CCJ2</sub>	CPU2_ITP Cycle to Cycle Jitter	Measured at 0V differential	_	125	ps
L <sub>ACC</sub>	Long-term Accuracy	Measured at 0V differential	_	100	ppm
T <sub>SKEW</sub>	CPU0 to CPU1 Clock Skew	Measured at 0V differential	-	100	ps
T <sub>SKEW2</sub>	CPU2_ITP to CPU0 Clock Skew	Measured at 0V differential	ı	150	ps
$T_R/T_F$	CPU Rising/Falling Slew rate	Measured differentially from ±150 mV	2.5	8	V/ns
T <sub>RFM</sub>	Rise/Fall Matching	Measured single-endedly from ±75 mV	ı	20	%
$V_{HIGH}$	Voltage High			1.15	V
$V_{LOW}$	Voltage Low		-0.3	-	V
V <sub>OX</sub>	Crossing Point Voltage at 0.7V Swing		300	550	mV
SRC at 0.7V					



# AC Electrical Specifications (continued)

Parameter	Description	Condition	Min.	Max.	Unit
T <sub>DC</sub>	SRC Duty Cycle	Measured at 0V differential		55	%
T <sub>PERIOD</sub>	100 MHz SRC Period	Measured at 0V differential at 0.1s	9.99900	10.0010	ns
T <sub>PERIODSS</sub>	100 MHz SRC Period, SSC	Measured at 0V differential at 0.1s	ed at 0V differential at 0.1s 10.02406 10.02		ns
T <sub>PERIODAbs</sub>	100 MHz SRC Absolute Period	Measured at 0V differential at 1 clock	9.87400	10.1260	ns
T <sub>PERIODSSAbs</sub>	100 MHz SRC Absolute Period, SSC	Measured at 0V differential at 1 clock	9.87406	10.1762	ns
T <sub>SKEW(window)</sub>	Any SRC Clock Skew from the earliest bank to the latest bank	Measured at 0V differential	_	3.0	ns
T <sub>CCJ</sub>	SRC Cycle to Cycle Jitter	Measured at 0V differential	-	125	ps
L <sub>ACC</sub>	SRC Long Term Accuracy	Measured at 0V differential	-	100	ppm
$T_R/T_F$	SRC Rising/Falling Slew Rate	Measured differentially from ±150 mV	2.5	8	V/ns
T <sub>RFM</sub>	Rise/Fall Matching	Measured single-endedly from ±75 mV	-	20	%
V <sub>HIGH</sub>	Voltage High			1.15	V
$V_{LOW}$	Voltage Low		-0.3	-	V
V <sub>OX</sub>	Crossing Point Voltage at 0.7V Swing		300	550	mV
DOT96 at 0.7\	i				
T <sub>DC</sub>	DOT96 Duty Cycle	Measured at 0V differential	45	55	%
T <sub>PERIOD</sub>	DOT96 Period	Measured at 0V differential at 0.1s	10.4156	10.4177	ns
T <sub>PERIODAbs</sub>	DOT96 Absolute Period	Measured at 0V differential at 0.1s	10.1656	10.6677	ns
T <sub>CCJ</sub>	DOT96 Cycle to Cycle Jitter	Measured at 0V differential at 1 clock	_	250	ps
L <sub>ACC</sub>	DOT96 Long Term Accuracy	Measured at 0V differential at 1 clock	-	100	ppm
T <sub>R</sub> / T <sub>F</sub>	DOT96 Rising/Falling Slew Rate	Measured differentially from ±150 mV	2.5	8	V/ns
T <sub>RFM</sub>	Rise/Fall Matching	Measured single-endedly from ±75 mV	_	20	%
$V_{HIGH}$	Voltage High			1.15	V
$V_{LOW}$	Voltage Low		-0.3	-	V
V <sub>OX</sub>	Crossing Point Voltage at 0.7V Swing		300	550	mV
LCD_100_SS	C at 0.7V		ľ		
T <sub>DC</sub>	LCD_100 Duty Cycle	Measured at 0V differential	45	55	%
T <sub>PERIOD</sub>	100 MHz LCD_100 Period	Measured at 0V differential at 0.1s	9.99900	10.0010	ns
T <sub>PERIODSS</sub>	100 MHz LCD_100 Period, SSC -0.5%	Measured at 0V differential at 0.1s	10.02406	10.02607	ns
T <sub>PERIODAbs</sub>	100 MHz LCD_100 Absolute Period	Measured at 0V differential at 1 clock	9.74900	10.25100	ns
T <sub>PERIODSSAbs</sub>	100 MHz LCD_100 Absolute Period, SSC	Measured at 0V differential at 1 clock	9.74906	10.3012	ns
T <sub>CCJ</sub>	LCD_100 Cycle to Cycle Jitter	Measured at 0V differential	_	250	ps
L <sub>ACC</sub>	LCD_100 Long Term Accuracy	Measured at 0V differential	-	100	ppm
T <sub>R</sub> / T <sub>F</sub>	LCD_100 Rising/Falling Slew Rate	Measured differentially from ±150 mV	2.5	8	V/ns
T <sub>RFM</sub>	Rise/Fall Matching	Measured single-endedly from ±75 mV	_	20	%
V <sub>HIGH</sub>	Voltage High			1.15	V
$V_{LOW}$	Voltage Low		-0.3	-	V
V <sub>OX</sub>	Crossing Point Voltage at 0.7V Swing		300	550	mV
PCI/PCIF at 3.	3V				
T <sub>DC</sub>	PCI Duty Cycle	Measurement at 1.5V	45	55	%
T <sub>PERIOD</sub>	Spread Disabled PCIF/PCI Period	Measurement at 1.5V	29.99700	30.00300	ns
T <sub>PERIODSS</sub>	Spread Enabled PCIF/PCI Period	Measurement at 1.5V	30.08421	30.23459	ns
	Spread Disabled PCIF/PCI Period	Measurement at 1.5V	29.49700	30.50300	+



# **AC Electrical Specifications** (continued)

Parameter	Description	Condition	Min.	Max.	Unit
T <sub>PERIODSSAbs</sub>	Spread Enabled PCIF/PCI Period	Measurement at 1.5V	29.56617	30.58421	ns
T <sub>HIGH</sub>	Spread Enabled PCIF and PCI high time	Measurement at 2V	12.27095	16.27995	ns
T <sub>LOW</sub>	Spread Enabled PCIF and PCI low time	Measurement at 0.8V	11.87095 16.07995		ns
T <sub>HIGH</sub>	Spread Disabled PCIF and PCI high time	Measurement at 2.V	12.27365 16.27665		ns
T <sub>LOW</sub>	Spread Disabled PCIF and PCI low time	Measurement at 0.8V	11.87365 16.07665		ns
T <sub>R</sub> / T <sub>F</sub>	PCIF/PCI Rising/Falling Slew Rate	Measured between 0.8V and 2.0V	1.0	4.0	V/ns
T <sub>SKEW</sub>	Any PCI clock to Any PCI clock Skew	Measurement at 1.5V	-	1000	ps
T <sub>CCJ</sub>	PCIF and PCI Cycle to Cycle Jitter	Measurement at 1.5V	-	500	ps
L <sub>ACC</sub>	PCIF/PCI Long Term Accuracy	Measurement at 1.5V	_	100	ppm
48_M at 3.3V					
T <sub>DC</sub>	Duty Cycle	Measurement at 1.5V	45	55	%
T <sub>PERIOD</sub>	Period	Measurement at 1.5V	20.83125	20.83542	ns
T <sub>PERIODAbs</sub>	Absolute Period	Measurement at 1.5V	20.48125	21.18542	ns
T <sub>HIGH</sub>	48_M High time	Measurement at 2V	8.216563	11.15198	ns
$T_{LOW}$	48_M Low time	Measurement at 0.8V	7.816563	10.95198	ns
T <sub>R</sub> / T <sub>F</sub>	Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	1.0	2.0	V/ns
T <sub>CCJ</sub>	Cycle to Cycle Jitter	Measurement at 1.5V	_	350	ps
L <sub>ACC</sub>	48M Long Term Accuracy	Measurement at 1.5V	_	100	ppm
27M_NSS/27M	1_SS at 3.3V		<u> </u>		
T <sub>DC</sub>	Duty Cycle	Measurement at 1.5V	45	55	%
T <sub>PERIOD</sub>	Spread Disabled 27M Period	Measurement at 1.5V	37.03594	37.03813	ns
	Spread Enabled 27M Period	Measurement at 1.5V	37.01299	37.13172	ns
T <sub>R</sub> / T <sub>F</sub>	Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	1.0	4.0	V/ns
T <sub>CCJ</sub>	Cycle to Cycle Jitter	Measurement at 1.5V	_	250	ps
L <sub>ACC</sub>	27_M Long Term Accuracy	Measured at crossing point V <sub>OX</sub>	_	50	ppm
REF	,		<u> </u>		
T <sub>DC</sub>	REF Duty Cycle	Measurement at 1.5V	45	55	%
T <sub>PERIOD</sub>	REF Period	Measurement at 1.5V	69.82033	69.86224	ns
T <sub>PERIODAbs</sub>	REF Absolute Period	Measurement at 1.5V	68.83429	70.84826	ns
T <sub>HIGH</sub>	REF High time	Measurement at 2V	29.97543	38.46654	ns
T <sub>LOW</sub>	REF Low time	Measurement at 0.8V	29.57543	38.26654	ns
T <sub>R</sub> / T <sub>F</sub>	REF Rising and Falling Edge Rate	Measured between 0.8V and 2.0V	1.0	4.0	V/ns
T <sub>SKEW</sub>	REF Clock to REF Clock	Measurement at 1.5V	_	500	ps
T <sub>CCJ</sub>	REF Cycle to Cycle Jitter	Measurement at 1.5V	_	1000	ps
L <sub>ACC</sub>	Long Term Accuracy	Measurement at 1.5V	_	100	ppm
	ABLE and SET-UP				
T <sub>STABLE</sub>	Clock Stabilization from Power-up		_	1.8	ms
T <sub>SS</sub>	Stopclock Set-up Time		10.0	-	ns
	1		1		l



## **Test and Measurement Set-up**

#### For PCI Single-ended Signals and Reference

The following diagram shows the test load configurations for the single-ended PCI, USB, and REF output signals.

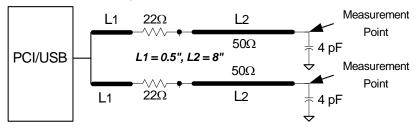


Figure 12. Single-ended PCI and USB Double Load Configuration

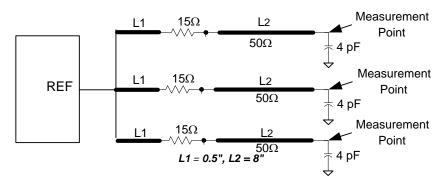


Figure 13. Single-ended REF Triple Load Configuration

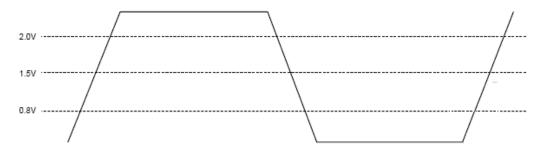


Figure 14. Single-ended Output Signals (for AC Parameters Measurement)



#### For CPU, SRC, and DOT96 Signals and Reference

This diagram shows the test load configuration for the differential CPU and SRC outputs

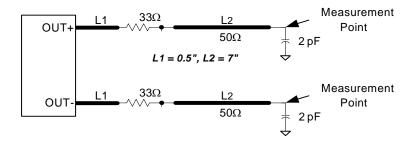


Figure 15. 0.7V Differential Load Configuration

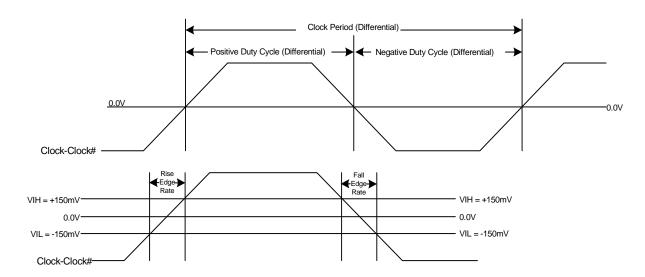


Figure 16. Differential Measurement for Differential Output Signals (for AC Parameters Measurement)



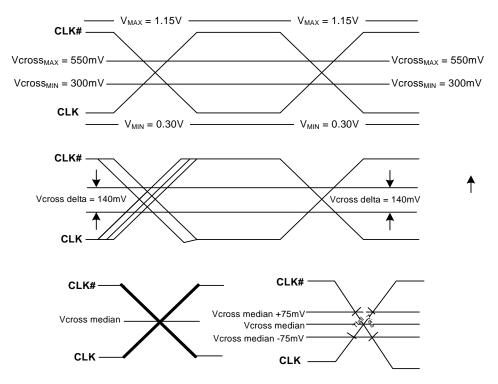


Figure 17. Single-ended Measurement for Differential Output Signals (for AC Parameters Measurement)

## **Ordering Information**

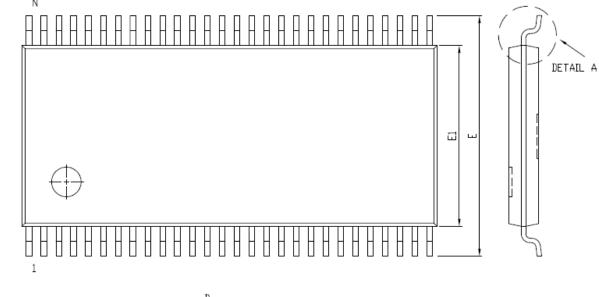
Part Number	Package Type	Product Flow
Lead-free		
SL28506BZC-2	56-pin TSSOP	Commercial, 0° to 85°C
SL28506BZC-2T	56-pin TSSOP-Tape and Reel	Commercial, 0° to 85°C
SL28506BZI-2	56-pin TSSOP	Industrial, -40° to 85°C
SL28506BZI-2T	56-pin TSSOP-Tape and Reel	Industrial, -40° to 85°C

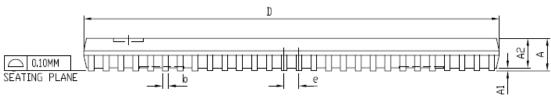
This device is Pb-free, Halogen-free and RoHS compliant. Parts supporting extended temperature is available upon request

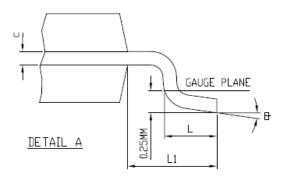


# **Package Diagrams**

## 56-Lead Thin Shrunk Small Outline Package







SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NDM	MAX.	MIN.	NDM	MAX.
Α			1.20			.047
A1	0.05		0.15	.002		.006
A2	0.80	1.00	1.05	.031	.039	.041
D	13,90	14.00	14.10	.547	551	,555
Е	8.00	8.10	8.20	.315	.319	.323
E1	6.00	6.10	6.20	.236	.240	.244
L	0,45	0.60	0.75	.018	.024	.030
L1	1	.00 REF.		.039 REF.		
b	0.18	0.20	0.25	.007	.008	.010
е	0	.50 BSC	1	),	050 B2C	
С	0.09		0.20	.004		,008
<del>-0</del>	0		8	0		8
N	56					
REF	JEDEC MO-153 VARIATION EE					

#### NOTES

- 1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
- 2, PACKAGE DUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
- 3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
- 4. LEAD COPLANARITY IS 0.003 INCH MAX.



#### **Document History Page**

Document Title: SL28506-2 Clock Generator for Intel <sup>®</sup> Eaglelake Chipset DOC #: SP-AP-0021 (Rev AB)					
REV.	ECR#	Issue Date	Orig. of Change	Description of Change	
1.0		7/12/07	JMA	New data sheet	
1.1		7/18/07	JMA	Merged TSSOP and SSOP into one datasheet	
1.2		7/19/07	JMA	Changed part number ordering information	
1.3		12/15/07	BSHEN	Changed part number ordering information to SL28506BZC Changed Revision ID to 0001	
1.4		6/18/08	JMA	Removed "Priliminary Confidential" wording     Changed operating temperature from 0C - 85C to 0C to 70C     Added Pb and ROHs compliant note	
1.5		10/23/08	JMA	Changed operating temperature back to 0-85C	
AA	1458	4/7/10	JMA	Added new feature for XIN to support also CLKIN input     Updated revision and ordering information     Updated JEDEC information     Updated format to be ISO compliant     Merged commercial and industrial temperature     Updated TSSOP package drawing     Removed SSOP package	
AB	1458	5/17/10	JMA	1. Added Bit 0 in Byte 3 2. Updated package ID in Byte 8 to reflect package 3. Updated Feature portion to include exclusion of SRC0 and SRC1 from PCIe Gen 2 requirements 4. Updated Byte 11 Bit 1 to be a read only bit 5. Added note to specified SRC0 and SRC1 are note PCIe Gen2 compliant. 6. Specified Byte 11 bit 1 is a read only bit.	

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